



Material Content Data Sheet



Sales Product Name		BTS244Z E3062A		Issued		13. February 2015		
MA#		MA000924708						
Package		PG-TO263-5-2		Weight*		1520.04 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	15.256	1.00	1.00	10036	10036
leadframe	non noble metal	iron	7439-89-6	0.790	0.05		519	
	inorganic material	phosphorus	7723-14-0	0.237	0.02		156	
wire	non noble metal	copper	7440-50-8	788.527	51.87	51.94	518755	519430
	non noble metal	aluminium	7429-90-5	1.825	0.12	0.12	1200	1200
encapsulation	organic material	carbon black	1333-86-4	8.714	0.57		5732	
	plastics	epoxy resin	-	95.849	6.31		63057	
leadfinish	inorganic material	silicondioxide	60676-86-0	476.339	31.34	38.22	313372	382161
	non noble metal	tin	7440-31-5	10.339	0.68	0.68	6802	6802
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.422	0.23	0.23	2251	2256
solder	noble metal	silver	7440-22-4	0.266	0.02		175	
	non noble metal	tin	7440-31-5	0.213	0.01		140	
heatspreader	non noble metal	lead	7439-92-1	10.177	0.67	0.70	6695	7010
	non noble metal	iron	7439-89-6	0.108	0.01		71	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	107.943	7.10	7.11	71013	71105
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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